



Click [here](#) for the 3D model.

Dimensions	
Chip Size	3640
L	9.3mm +/-0.6mm
W	10.2mm +/-0.4mm
T	2.5mm +/-0.20mm
B	1.27mm +/-0.4mm

  

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	1000

General Information	
Series	KC-LINK Comm COG
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	1.06 g
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	0.047 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	500 VDC
Dielectric Withstanding Voltage	750 VDC
Temperature Range	-55/+150°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	21.2766 GOhms